

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ravi Shankar	04/07/2010
Olivier Le Neel	04/07/2010
RECEIVING PARTY DATA	
Name:	STMicroelectronics Asia Pacific Pte. Ltd.
Street Address:	5A Serangoon North Avenue 5
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	554574
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12650257
CORRESPONDENCE DATA	
Fax Number:	(206)682-6031
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	206-622-4900
Email:	laurah@seedip.com
Correspondent Name:	Harold H. Bennett II
Address Line 1:	701 Fifth Avenue
Address Line 2:	Suite 5400
Address Line 4:	Seattle, WASHINGTON 98104
ATTORNEY DOCKET NUMBER:	851663.490
NAME OF SUBMITTER:	Harold H. Bennett II
Total Attachments: 2 source=490_ASSIGN#page1.tif source=490_ASSIGN#page2.tif	

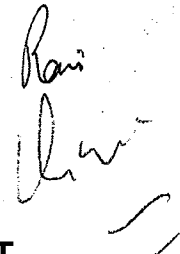
CH \$40.00 12650257

ASSIGNMENT

WHEREAS, we, Ravi Shankar and Olivier Le Neel (hereinafter referred to as ASSIGNORS), having mailing addresses of 28, Ang Mo Kio Industrial Park II, Singapore, Singapore 569508 and 9019 Bottlebrush, Irving, Texas 75063, respectively, are the joint inventors of an invention entitled "DEVICE AND METHOD FOR TESTING MAGNETIC SWITCHES AT WAFER-LEVEL STAGE OF MANUFACTURE," as described and claimed in the specification for which an application for United States letters patent was filed on December 30, 2009, and assigned Application No. 12/650,257;

WHEREAS, STMicroelectronics Asia Pacific Pte. Ltd. (hereinafter referred to as ASSIGNEE), a corporation of the country of Singapore and having a place of business at 5A Serangoon North Avenue 5, Singapore, Singapore 554574, is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefor in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions including any extensions or adjustments in term thereof and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding letters patent, or for the purpose of protecting title to said invention or letters patent therefor.



7-Apr-2010

Date

Ravi Shankar

Ravi Shankar

7-Apr-2010

Date

Olivier Le Neel

Olivier Le Neel

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